



US00D401567S

United States Patent [19]

Farnworth et al.

[11] Patent Number: Des. 401,567
[45] Date of Patent: **Nov. 24, 1998

[54] TEMPORARY PACKAGE FOR SEMICONDUCTOR DICE
[75] Inventors: Warren M. Farnworth, Nampa; Alan G. Wood, Boise; David R. Hembree, Boise; Salman Akram, Boise, all of Id.

[73] Assignee: Micron Technology, Inc., Boise, Id.
[**] Term: 14 Years

[21] Appl. No.: 70,005
[22] Filed: Apr. 25, 1997

[51] LOC (6) Cl. 13-03
[52] U.S. Cl. D13/182
[58] Field of Search D13/182; 324/755, 324/765; 437/209

[56] References Cited

U.S. PATENT DOCUMENTS

D. 394,844	6/1998	Farnworth et al.	D13/182
5,173,451	12/1992	Kinsman et al.	437/209
5,302,891	4/1994	Wood et al.	324/158 F
5,408,190	4/1995	Wood et al.	324/865
5,440,240	8/1995	Wood et al.	324/765
5,451,165	9/1995	Cearley-Cabbiness et al.	439/71
5,495,179	2/1996	Wood et al.	324/755
5,517,125	5/1996	Posedel et al.	324/755

5,519,332	5/1996	Wood et al.	324/755
5,530,376	6/1996	Lim et al.	324/765
5,541,525	7/1996	Wood et al.	324/755
5,543,725	8/1996	Lim et al.	324/755
5,581,195	12/1996	Lee et al.	324/755
5,742,169	4/1998	Akram et al.	324/755

OTHER PUBLICATIONS

Van Zant, Peter, *Microchip Fabrication—A Practical Guide To Semiconductor Processing*, Second Edition, 1990, pg. 493.

Primary Examiner—Brian N. Vinson
Attorney, Agent, or Firm—Stephen A. Gratton

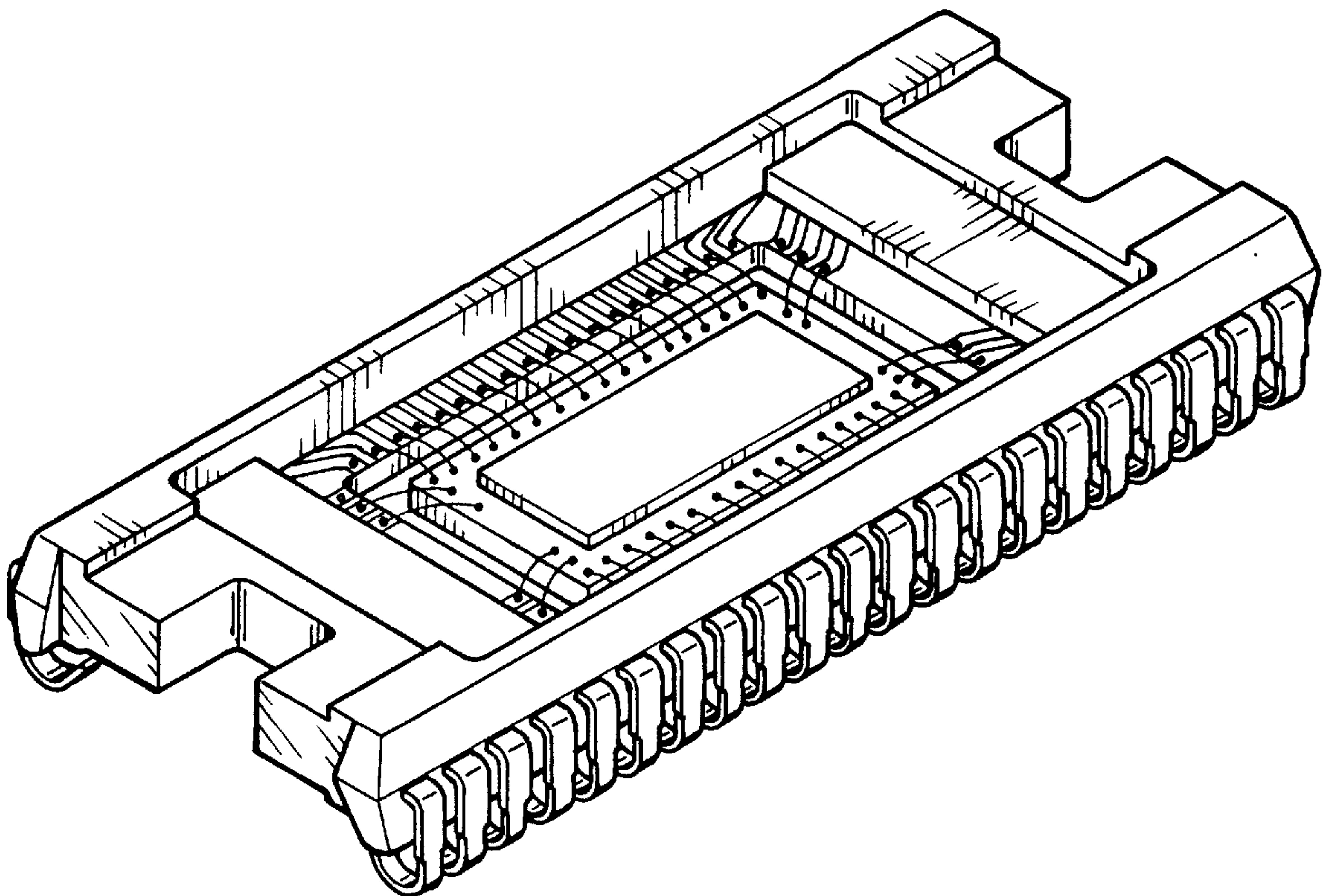
[57] CLAIM

The ornamental design for a temporary package for testing semiconductor dice, as shown and described.

DESCRIPTION

FIG. 1 is an enlarged top perspective view of a temporary package for semiconductor dice showing my new design; FIG. 2 is a left side elevational view thereof; FIG. 3 is a right side elevational view thereof; FIG. 4 is a top plan view thereof; FIG. 5 is a front side elevational view thereof; FIG. 6 is a bottom plan view thereof; and, FIG. 7 is a rear side elevation view thereof.

1 Claim, 2 Drawing Sheets



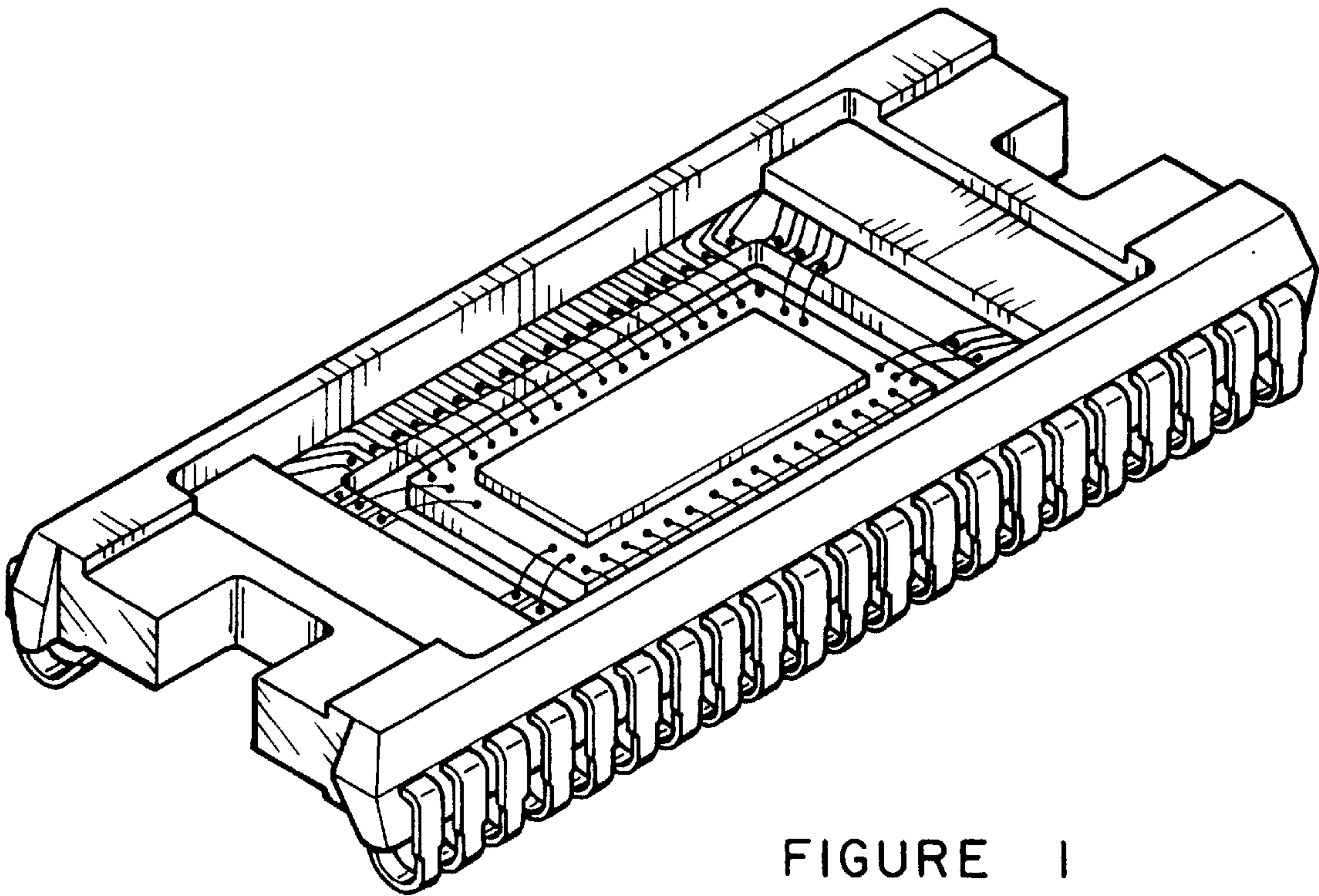


FIGURE 1

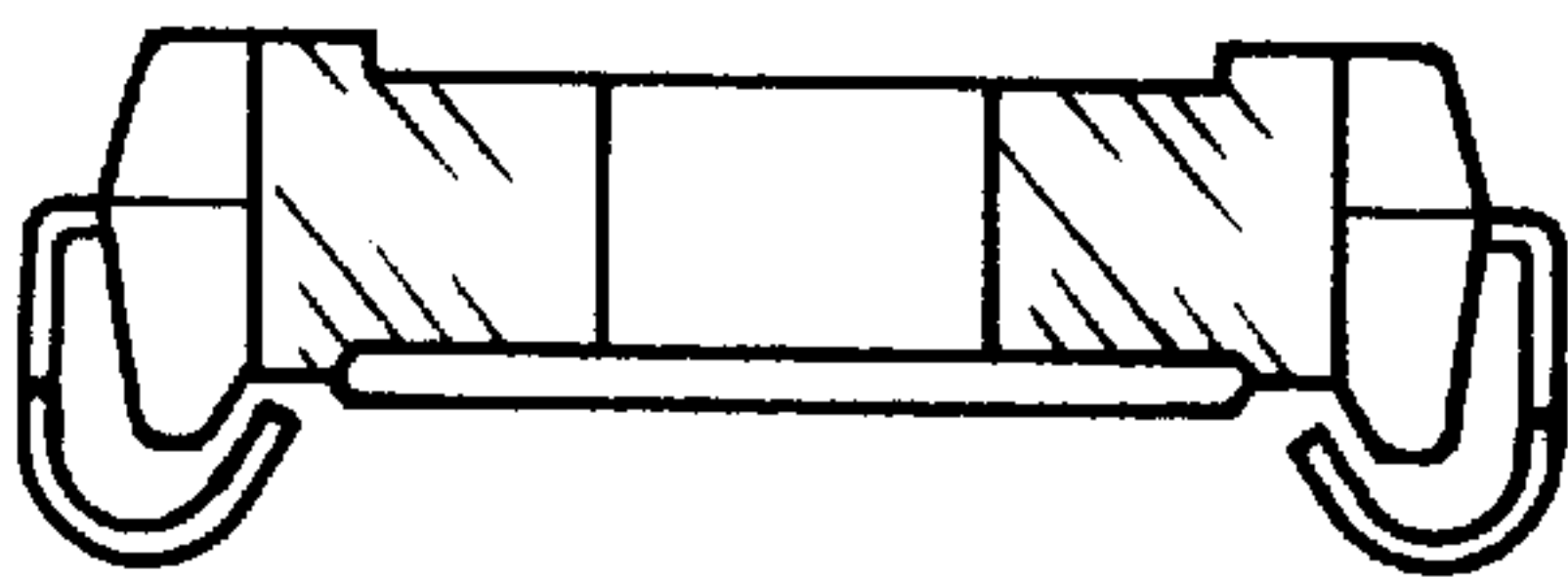


FIGURE 2

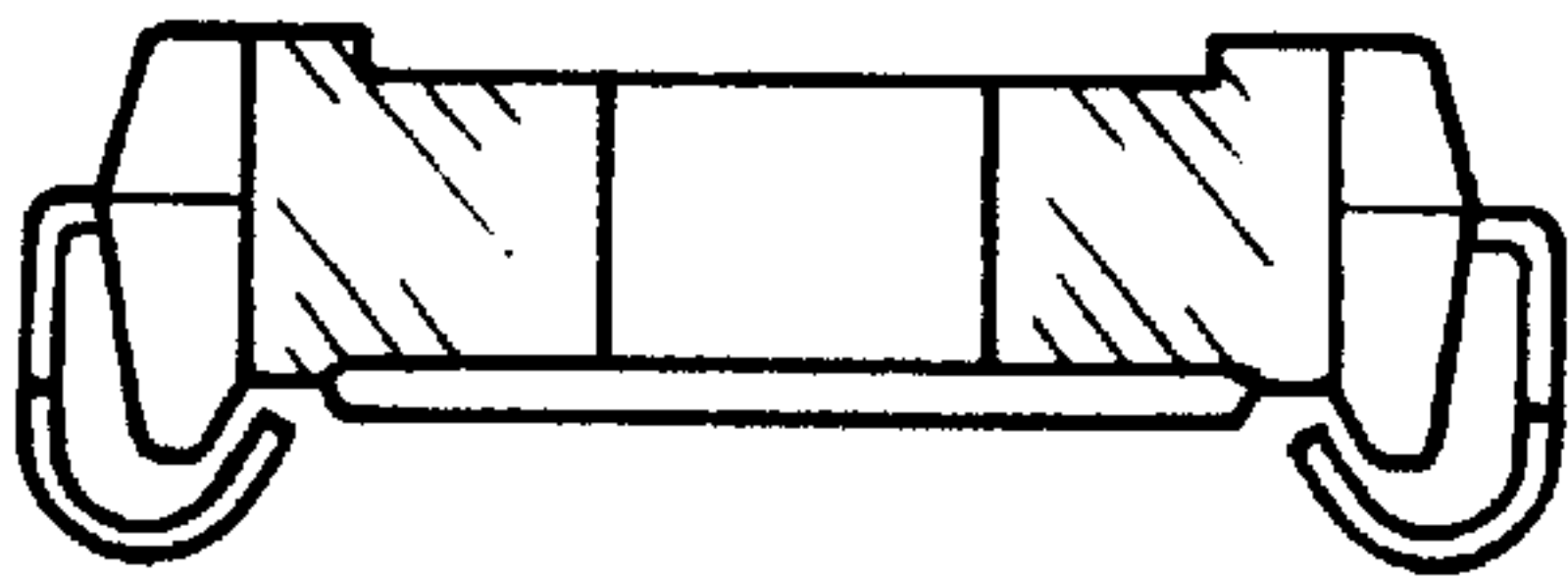


FIGURE 3

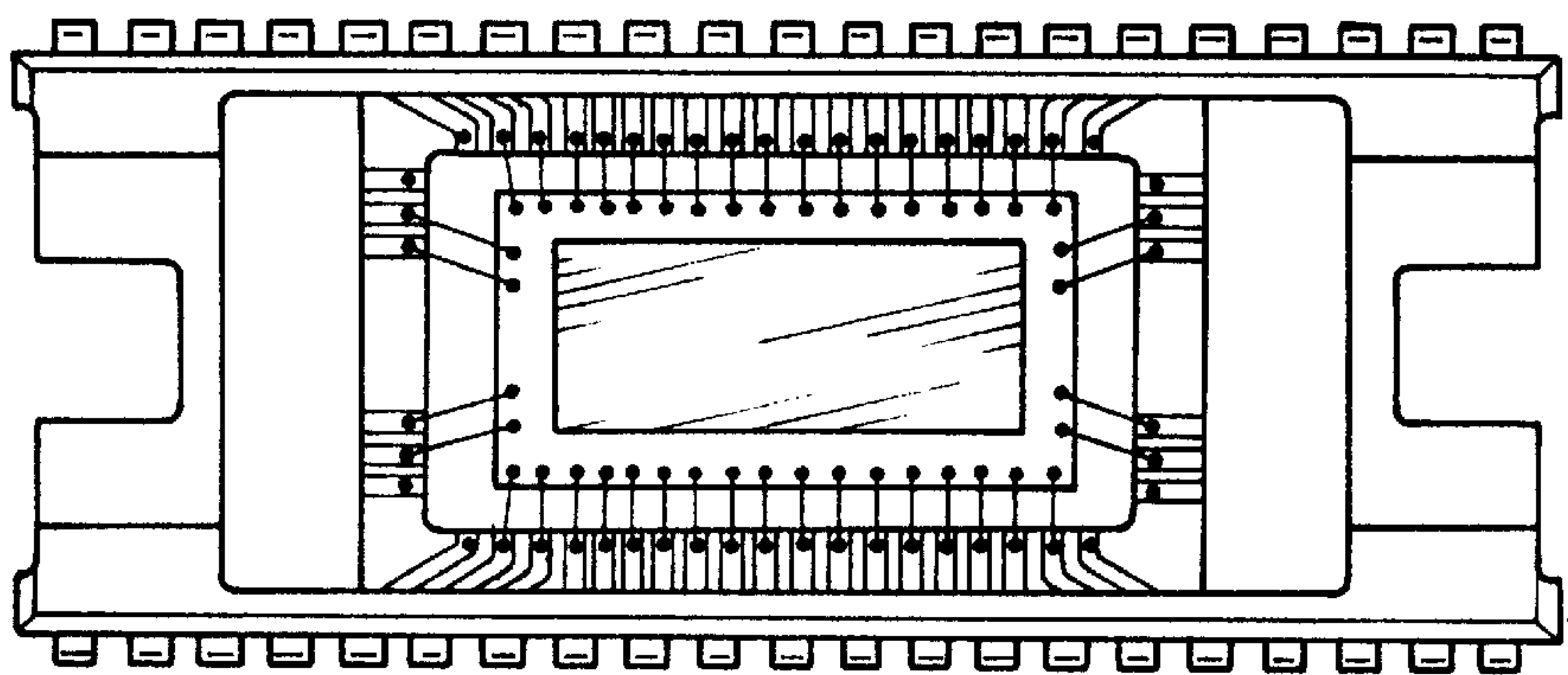


FIGURE 4

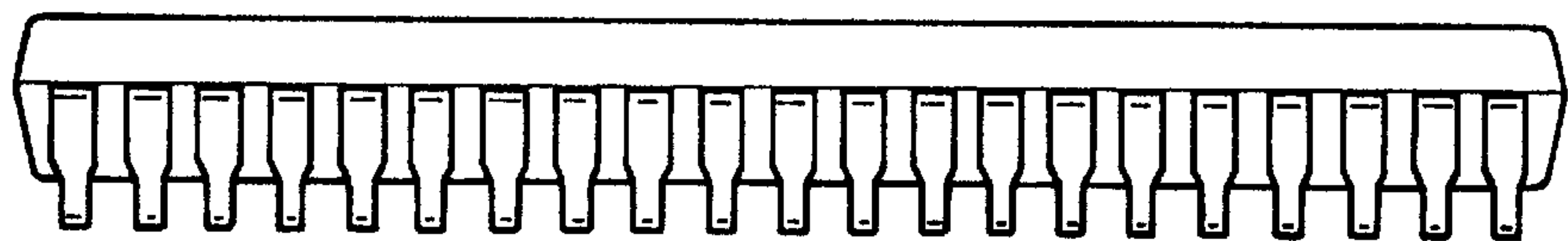


FIGURE 5

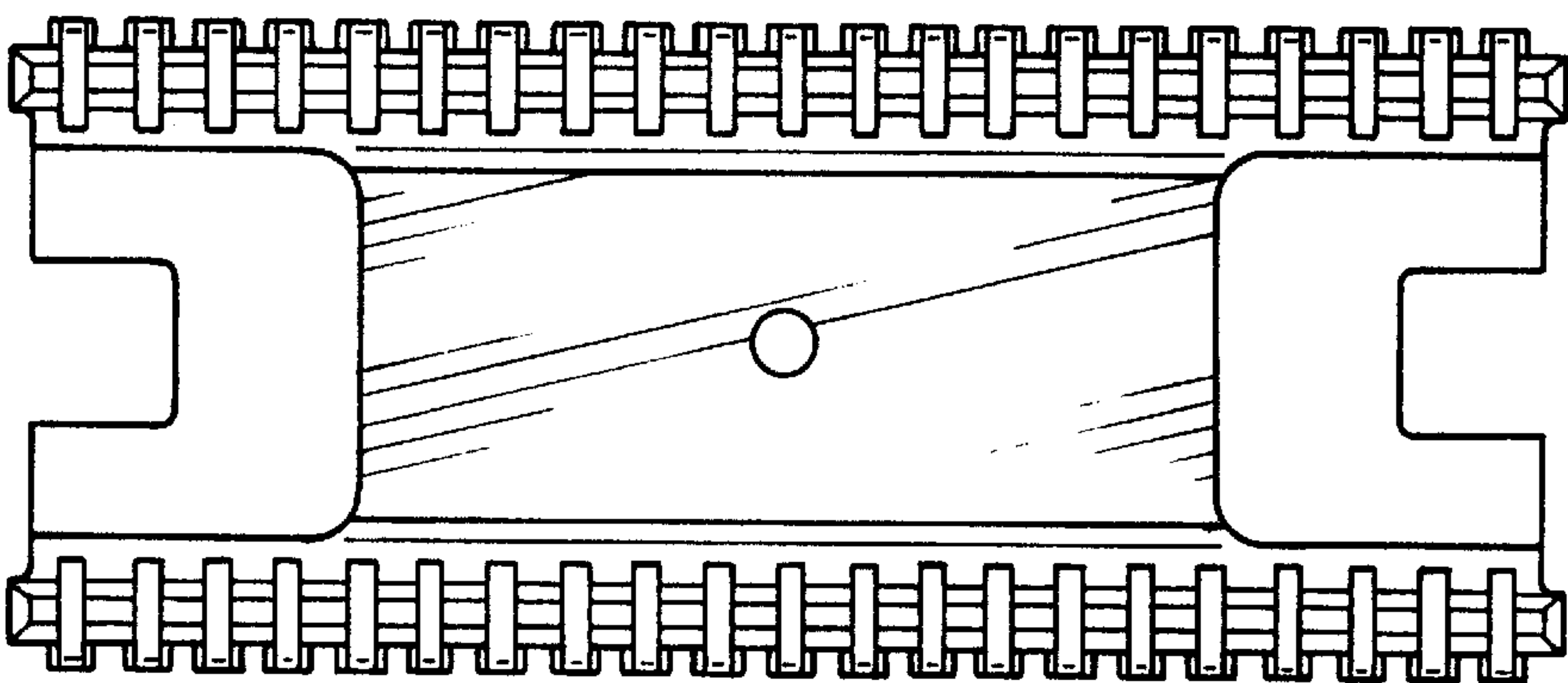


FIGURE 6

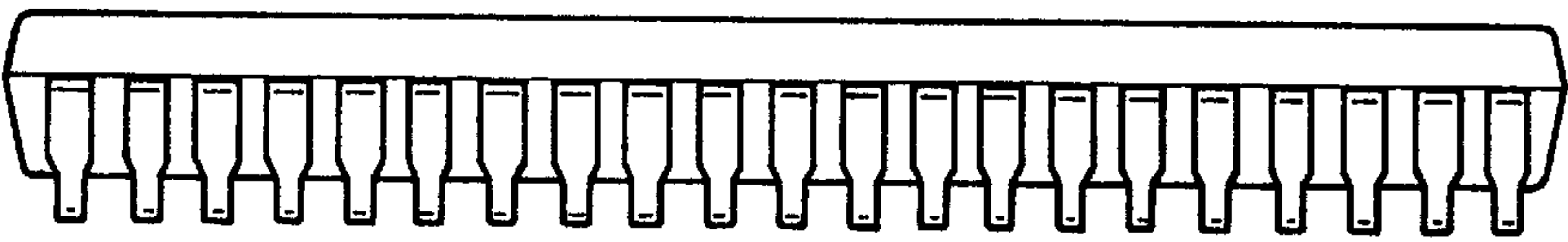


FIGURE 7